

**IN THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 2 and 4 have been canceled, claims 1, 3, 5-8 and 10 have been amended and claims 15-20 have been added as follows:

**Listing of Claims:**

Claim1 (currently amended): A heat-treated resin molding obtained by heat-treating a specific portion of a resin molding (W) partially at a high temperature which specific portion is apt to undergo peeling of a thin surface resin film of the resin molding (W) resin molding (W) partially at a high temperature, the resin molding (W) being produced by molding with use of a mold and to be subjected to plating with resin.

Claim 2 (canceled)

Claim 3 (currently amended): A heat-treated resin molding according to claim 1 ~~or claim 2~~, wherein a parting line portion (W1) of the resin molding (W) is heat-treated at a high temperature.

Claim 4 (canceled)

Claim 5 (currently amended): A heat-treated resin molding according to ~~any of claims 1 to 4~~ claim 1, wherein the resin molding (W) is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a generally circular shape.

Claim 6 (currently amended): A heat-treated resin molding according to ~~any of claims 1 to 4~~ claim 1, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface

of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 7 (currently amended): A heat-treated resin molding according to ~~any of claims 1 to 4~~ claim 1, wherein the resin molding (W) to be partially heat-treated at a high temperature is a resin molding produced by molding in an injection molding machine.

Claim 8 (currently amended): A resin molding heat-treating apparatus (1) for heat-treating a parting line portion (W1) of a resin molding (W) or a specific ~~portion~~ portion of the resin molding (W), which portion is apt to undergo peeling of a thin surface resin film, partially at a high temperature,

the apparatus (1) comprising:

heating section (2) having a shape conforming to a contour line of a portion to be heated of the resin molding (W); and

a fixing jig (4) for fixing the resin molding (W) removably,

wherein the portion to be heated of the resin molding (W) is heat-treated at a high temperature while being approximated to the heating section (2).

Claim 9 (original): A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a rotary disc (3) and the portion to be heated of the resin molding (W) projects from the peripheral edge of the rotary disc (3) so as to pass through a heat-treating space (S) formed in the heating section (2).

Claim 10 (currently amended): A resin molding heat-treating apparatus according to claim 8 ~~or claim 9~~, wherein a shield plate (8) having an opening portion (7) of a shape conforming to the contour line of the portion to be heated of the resin molding (W) is disposed in a sandwiching relation to the heating section (2) so that the other portion than the portion to be heated of the resin molding (W) is not heated.

Claim 11 (original): A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a side edge of a belt member and the portion to be heated of the resin molding (W) projects from the belt member so as to pass through a heat-treating space (S) formed in the heating section (2).

Claim 12 (original): A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a large number of fine holes are formed in a pipe which is analogous to the contour line of the resin molding (W) and which is bent so as to be in a shape about twice as large as the resin molding (W), and hot air is ejected through the fine holes to heat the resin molding.

Claim 13 (original): A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the resin molding (W) and having a shape about twice as large as the resin molding (W) is heated by an electromagnetic induction heating method.

Claim 14 (original): A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the resin

molding (W) and having a shape about twice as large as the resin molding (W) is heated by a high-frequency heating method.

Claim 15 (new): A heat-treated resin molding according to claim 3, wherein the resin molding (W) is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a generally circular shape.

Claim 16 (new): A heat-treated resin molding according to claim 3, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 17 (new): A heat-treated resin molding according to claim 5, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 18 (new): A heat-treated resin molding according to claim 15, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 19 (new): A heat-treated resin molding according to claim 3, wherein the resin molding (W) to be partially heat-treated at a high temperature is a resin molding produced by molding in an injection molding machine.

Claim 20 (new): A resin molding heat-treating apparatus according to claim 9, wherein a shield plate (8) having an opening portion (7) of a shape conforming to the contour line of the portion to be heated of the resin molding (W) is disposed in a sandwiching relation to the heating

section (2) so that the other portion than the portion to be heated of the resin molding (W) is not heated.